

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (previously presented) An electronic assembly comprising at least a first integrated electronic module, the first module including at least one interconnection means for optical connection to a printed circuit card or to a second electronic module, the assembly including a soleplate and heat removal means for removing heat from said module via a first face of said module to the soleplate, and wherein the soleplate is independent of the interconnection means of the first module; and wherein the first face of said module is distinct from a second face of said module that contacts said soleplate.

2. (original): An assembly according to claim 1, wherein the interconnection means includes an optical fiber.

3. (previously presented) An assembly according to claim 2, wherein the optical fiber is included in a printed circuit card, and wherein a first end of the fiber is mounted in register with an optical contact of the first module by means of balls bonded to the module and disposed with precision relative to metal areas of the printed circuit card.

4. (original): An assembly according to claim 9, wherein the interconnection means includes a flexible printed circuit.

5. (original): An assembly according to claim 1, wherein the interconnection means includes a printed circuit card portion connected to the first module and a second printed circuit card portion connected to the second module, the two cards being interconnected by a second interconnection means.

6. (original): An assembly according to claim 5, wherein the two cards are secured to each other and the second interconnection means is constituted by tracks interconnecting the two card portions.

7. (original): An assembly according to claim 5, wherein the interconnection means includes a flexible printed circuit.

8. (currently amended): An assembly according to claim 1, wherein the interconnection means includes a conductive matrix of the conductive matrix of the modified circuit board between the module and the printed circuit card

9. (previously presented) An electronic assembly comprising at least a first integrated electronic module, the first module comprising at least one interconnection means for optical connection to a printed circuit card or to a second electronic module, the assembly further comprising a soleplate and a heat removal system that removes heat from said first module to the soleplate, and wherein the soleplate is independent of the interconnection means of the first module; wherein the heat removal system comprises a first segment and a second segment, the first segment connecting an integrated circuit of the first module to a first face of the first module, the first face being distinct from a second face making contact between the first module and the soleplate, and the second segment connecting said second face to the soleplate.

10. (original): An assembly according to claim 9, wherein the first segment comprises a heat conductive channel.

11. (previously presented) An assembly according to claim 9, wherein the second segment comprises a closed heat pipe containing a fluid.

12. (original): An assembly according to claim 9, wherein the second segment comprises a cylindrical tube having a fluted inside wall.

13 (previously presented) The assembly according to claim 3, wherein the first end of the optical fiber includes an etched lens.

14 (previously presented) The assembly according to claim 11, wherein the fluid is one of water, alcohol, and a combination of water and alcohol.

15. (previously presented) The assembly according to claim 9, wherein the interconnection means includes an optical fiber.

16. (previously presented) The assembly according to claim 15, wherein the optical fiber is included in a printed circuit card, and wherein a first end of the fiber is mounted in register with an optical contact of the first module by means of balls bonded to the module and disposed with precision relative to metal areas of the printed circuit card.

17. (previously presented) The assembly according to claim 9, wherein the interconnection means includes a flexible printed circuit.

18. (previously presented) The assembly according to claim 9, wherein the interconnection means includes a printed circuit card portion connected to the first module and a

second printed circuit card portion connected to the second module, the two cards being interconnected by a second interconnection means.

19. (previously presented) The assembly according to claim 18, wherein the two cards are secured to each other and the second interconnection means is constituted by tracks interconnecting the two card portions.

20. (previously presented) The assembly according to claim 18, wherein the second interconnection means is a flexible printed circuit.

21. (currently amended): The assembly according to claim 9, wherein the interconnection means comprise a contact matrix, the contact matrix being mounted, ~~for~~ ~~example,~~ between the module and the printed circuit card.

22. (previously presented) An electronic assembly comprising at least a first integrated electronic module, the first module comprising at least one interconnection that connects to a printed circuit card or to a second electronic module, the assembly further comprising a soleplate and a heat removal system that removes heat from said first module to the soleplate, and wherein the soleplate is independent of the interconnection of the first module; wherein the heat removal

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system comprises a first segment and a second segment, the first segment connecting an integrated circuit of the first module to a first face of the first module, the first face being distinct from a second face making contact between the first module and the soleplate, and the second segment connecting said second face to the soleplate.